

NOTICE INVITING BIDS

The Peralta Community College District is calling for sealed bids for the **Leak Remediation for Laney College Buildings A, F, & G – Phase 2 (Bid No. 17-18/28)** to be delivered to the Purchasing Department lobby, at 501 5th Avenue, Oakland, California, 94606, until **2:00 pm, on March 20, 2018**.

This project could require night time hours but will require weekend work hours.

This is a Public Works project and will require payment of prevailing wages. A Project Labor Agreement (PLA) is required for this project. The successful Bidder will be required to sign a Letter of Assent agreeing to the terms and conditions of the District's PLA. In order to perform the work, Bidders at the time of the Bid Opening and for the duration of the project shall possess a valid California Contractor's license and certifications in order to qualify to perform the Work: **Class B** General Building Contractors License. The Laney College Leak Remediation project includes demolition of concrete topping slabs, planters, irrigation lines, waterproofing, expansion joints, flashings, and associated materials; providing new topping slab and reinforcement; performing flashing repairs at doors and windows; and providing new drain bowls and miscellaneous plumbing line repairs at selected buildings, courtyards and walkways with the Construction Documents prepared by Allana Buick & Bers (ABB), Inc.

A **mandatory** bidders' conference and site walk will be held on **March 6, 2018** at 10:00 a.m. on Laney Campus on the upper podium deck of Building F, 900 Fallon Street, Oakland, CA 94607.

All bids shall be presented in accordance with the bid specifications for this project. Bid documents and specifications will be available for purchase by **February 23, 2018** at cost from East Bay Blueprint, 1475 Fourteenth Ave, Oakland, CA, 94606, phone number 510-261-2990, and on-line at ebbp@eastbayblueprint.com , or by visiting our website at www.peralta.edu and under "Quick Links", click "Business Opportunities" to download the bid packet

Publication Dates: 2/23/18 and 3/2/18.